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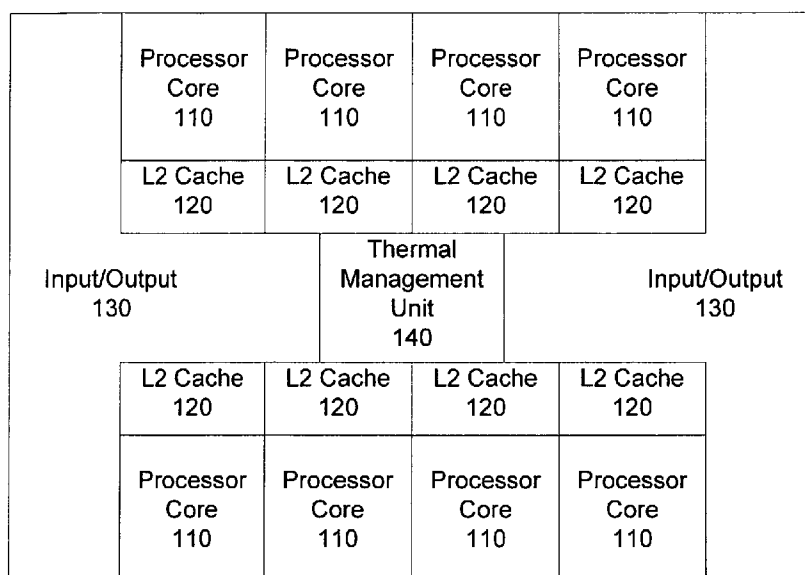
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(54) Title: AN APPARATUS FOR THERMAL MANAGEMENT OF MULTIPLE CORE MICROPROCESSORS



(57) Abstract: An apparatus for managing the temperature of an integrated circuit having a multiple core microprocessor is described. Specifically, thermal sensors are placed at potential hot spots throughout each microprocessor core. A thermal management unit monitors the thermal sensors. If a thermal sensor identifies a hot spot, the thermal management unit adjusts the operating frequency and voltage of that microprocessor core accordingly.



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